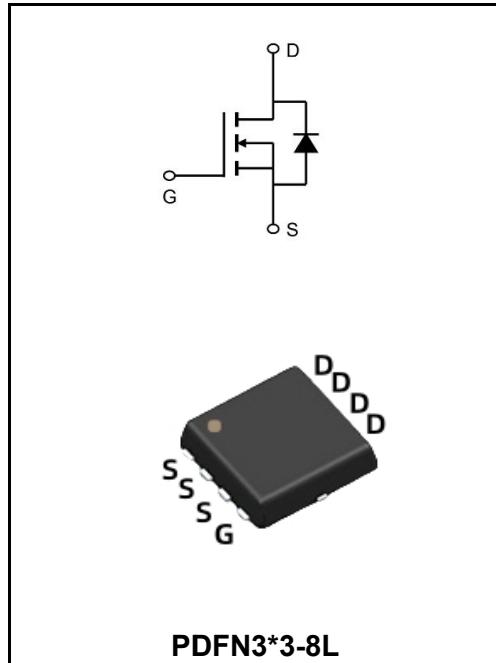


**20V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	20A
$V_{DSS}$	20V
$R_{DS(ON)}\text{-typ}(@V_{GS}=4.5V)$	<8.0mΩ (Typ:6.2 mΩ)
$R_{DS(ON)}\text{-typ}(@V_{GS}=2.5V)$	<11mΩ (Typ:8.2 mΩ)


**Description**

The YFW20N02DF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a battery protection or in other Switching application.

**Application**

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Characteristics		Symbols	Value	Units
Drain-Source Voltage		$V_{DS}$	20	V
Gate - Source Voltage		$V_{GS}$	±12	V
Continuous Drain Current	@ $T_c=25^\circ C$	$I_D$	20	A
Continuous Drain Current	@ $T_c=100^\circ C$	$I_D$	15	A
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	60	A
Single Pulse Avalanche Energy <sup>2</sup>		$E_{AS}$	36	mJ
Power dissipation	$T_c=25^\circ C$	$P_D$	31	W
Thermal Resistance Junction-Case		$R_{\theta JC}$	4.84	°C/W
Storage Temperature Range		$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range		$T_J$	-55 to +150	°C

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	$\text{BV}_{DSS}$	20	22	-	<b>V</b>
Drain-Source Leakage Current	$V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$	$I_{DSS}$	-	-	1.0	$\mu\text{A}$
Gate-Source Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 12\text{V}$	$I_{GSS}$	-	-	$\pm 100$	$\text{nA}$
Gate -Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	$V_{GS(\text{th})}$	0.5	0.75	1.0	<b>V</b>
Drain-source on-state resistance <sup>3</sup>	$V_{GS}=4.5\text{V}$ , $I_D=25\text{A}$	$R_{DS(\text{ON})}$	-	6.2	8.0	$\text{m}\Omega$
	$V_{GS}=2.5\text{V}$ , $I_D=10\text{A}$		-	8.2	11	
Input Capacitance	$V_{DS}=10\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$	$C_{iss}$	-	1458	-	$\text{pF}$
Output Capacitance		$C_{oss}$	-	238	-	
Reverse Transfer Capacitance		$C_{rss}$	-	212	-	
Total Gate Charge	$V_{DS}=10\text{V}$ $I_D=25\text{A}$ $V_{GS}=4.5\text{V}$	$Q_g$	-	19	-	$\text{nC}$
Gate-Source Charge		$Q_{gs}$	-	3	-	
Gate Drain("Miller") Charge		$Q_{gd}$	-	6.4	-	
Turn-On Delay Time	$V_{DS}=10\text{V}$ , $I_D=10\text{A}$ , $R_{GEN}=3\Omega$ , $V_{GS}=4.5\text{V}$	$t_{d(on)}$	-	10	-	$\text{ns}$
Rise Time		$T_r$	-	21	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	39	-	
Fall Time		$t_f$	-	19	-	
Maximum Continuous Drain to Source Diode Forward Current		$I_s$	-	-	50	<b>A</b>
Maximum Pulsed Drain to Source Diode Forward Current		$I_{SM}$	-	-	200	<b>A</b>
Diode Forward Voltage	$V_{GS} = 0\text{V}$ , $I_s = 30\text{A}$	$V_{SD}$	-	-	1.2	<b>V</b>
Body Diode Reverse Recovery Time	$I_F = 20\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$	$trr$		25		$\text{ns}$
Body Diode Reverse Recovery Charge		$Qrr$		20		$\text{nC}$

Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The EAS condition:  $T_J=25^\circ\text{C}$ ,  $VDD=16\text{V}$ ,  $V_G=10\text{V}$ ,  $R_G=0.6\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=33\text{A}$
- 4、The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

### Typical Characteristics

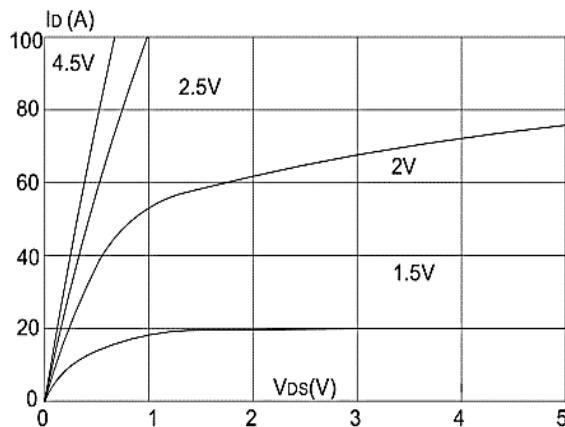


Figure 1: Output Characteristics

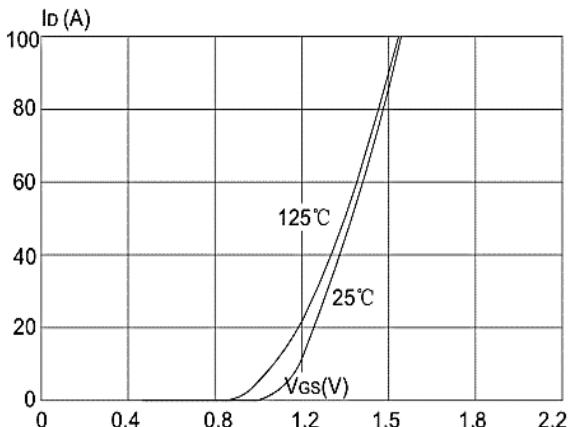


Figure 2: Typical Transfer Characteristics

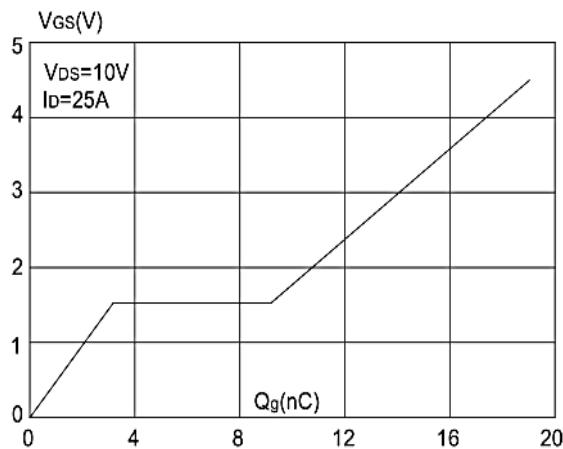


Figure 3: On-resistance vs. Drain Current

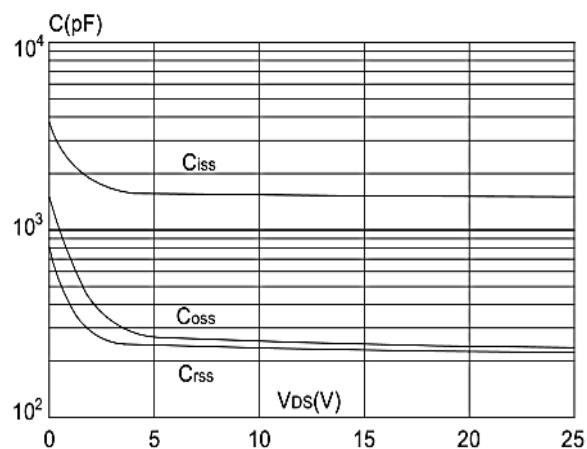


Figure 4: Body Diode Characteristics

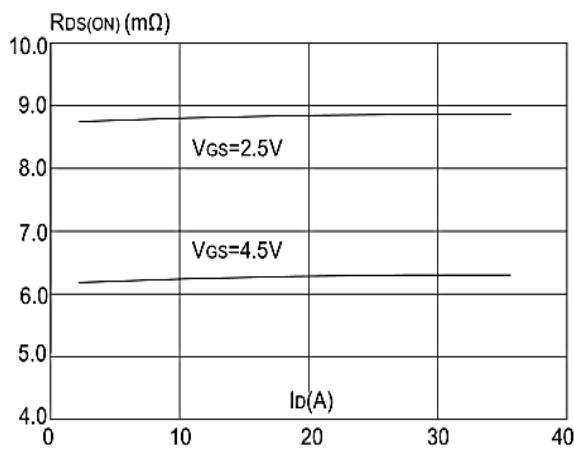


Figure 5: Gate Charge Characteristics

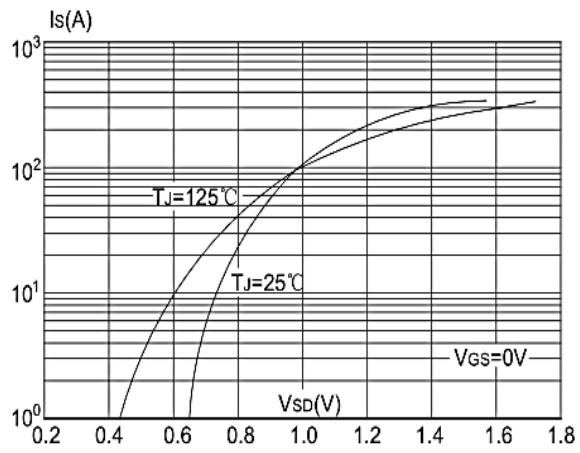
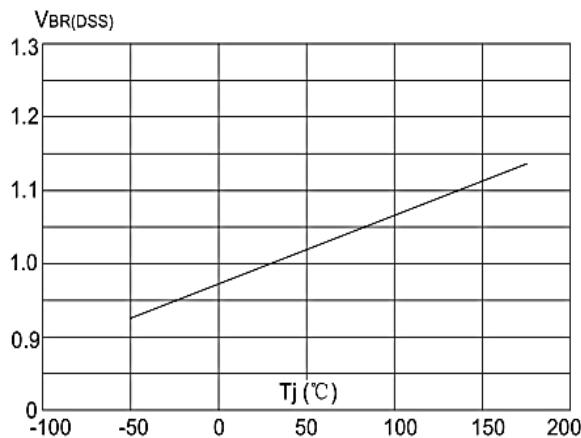
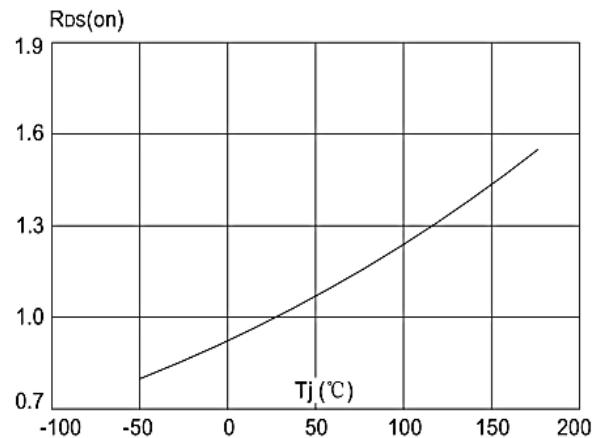


Figure 6: Capacitance Characteristics

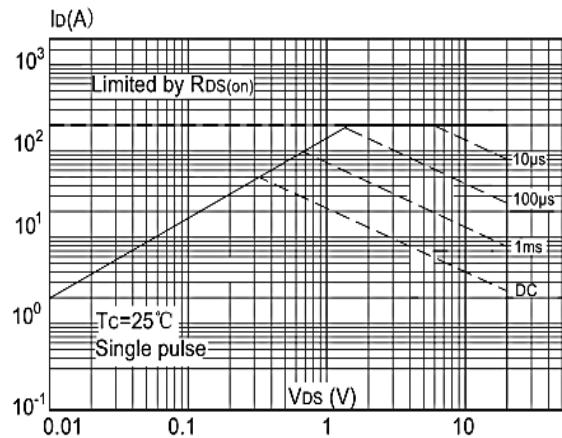
### Typical Characteristics



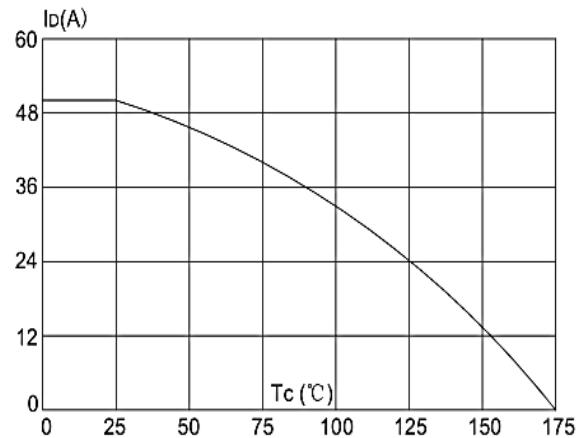
**Figure 7: Normalized Breakdown Voltage vs Junction Temperature**



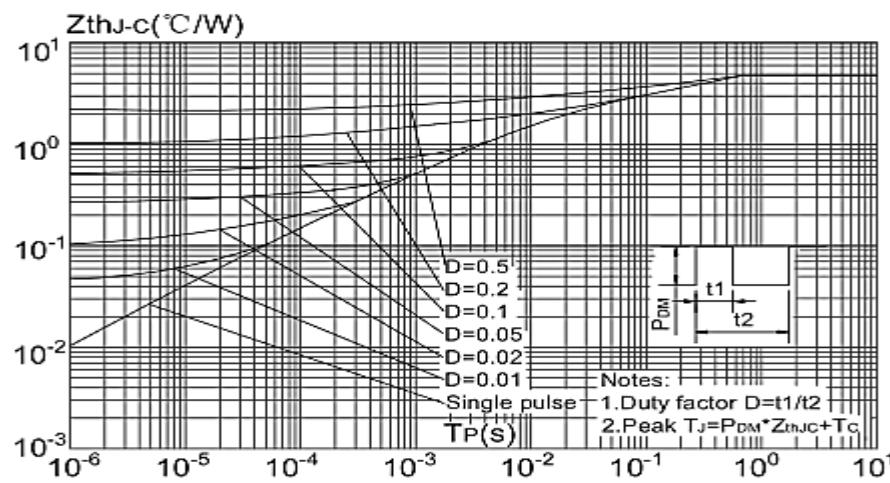
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area**

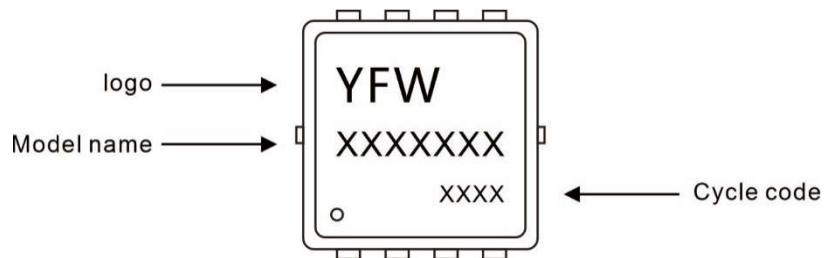


**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**



**Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**

### Marking Diagram



### Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFW20N02DF	PDFN3*3-8L	0.0023oz(0.065g)	5000pcs/reel	10000pcs/box 50000pcs/Carton

### Package Dimensions

#### PDFN3\*3-8L

Dim	Millimeter		mil	
	Min.	Max.	Min.	Max.
A	0.70	0.85	0.0276	0.0335
A1	-	0.05	-	0.002
b	0.20	0.40	0.008	0.016
c	0.10	0.25	0.004	0.010
D	3.15	3.45	0.124	0.136
D1	3.00	3.25	0.118	0.128
D2	2.29	2.65	0.09	0.104
E	3.15	3.45	0.124	0.136
E1	2.90	3.20	0.114	0.126
E2	1.54	1.94	0.061	0.076
E3	0.28	0.65	0.011	0.026
E4	0.37	0.77	0.015	0.030
E5	0.10	0.30	0.004	0.012
e	0.60	0.70	0.024	0.028
K	0.59	0.89	0.023	0.035
L	0.30	0.50	0.012	0.020
L1	0.06	0.20	0.002	0.008
t	-	0.13	-	0.005
Φ	10°C	14°C	10°C	14°C

## Disclaimer

The information presented in this document is for reference only. GuangDong Youfeng Microelectronics Co.,Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise. The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices). YFW or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale. This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <https://www.yfwdiode.com>, or consult YFW sales office for further assistance.